Listing of Claims

The following listing of claims will replace all prior versions, and listings, of claims in the subject application:

Claims 1-12 (canceled).

13. (currently amended) A method of preparing a heat-sensitive stencil comprising a porous resin layer, and a resin film laminated on said porous resin layer, and a thin resin layer interposed between said porous resin layer and said resin film, ~~said thin resin layer and said porous resin layer forming a continuous unitary body,~~ said method comprising the steps of:

D1

applying a wet coating composition to a surface of said resin film, said wet composition containing a resin, a first solvent capable of dissolving said resin, and a second solvent substantially incapable of dissolving said resin;

applying heat to said composition at a temperature below a boiling point of said second solvent and sufficient to vaporize at least part of said first solvent; and

drying said applied composition by applying heat to said composition at a temperature sufficient to completely vaporize said first solvent and said second solvent to form said thin resin layer and said porous layer simultaneously as a continuous unitary body on said surface of said film.

14. (currently amended) A method as set forth in claim 13, wherein the weight ratio of said first ~~resin~~ solvent to said second ~~resin~~ solvent is greater than 1:1.

15. (previously presented) A method of preparing a heat-sensitive stencil comprising a porous resin layer, and a resin film laminated on said porous resin layer, and a thin resin layer interposed between said porous resin layer and said resin film, said method comprising the steps of:

applying a first coating composition to a surface of said resin film,

drying said applied first composition to form said thin resin layer on said surface of said film,

applying a second coating composition to a surface of said thin resin layer, and

drying said applied second composition to form said porous resin layer on said surface of said thin resin layer.

Claims 16-18 (canceled).

19. (previously presented) A method of preparing a heat-sensitive stencil comprising a porous resin layer, and a resin film laminated on the porous resin layer, and a thin resin layer interposed between the porous resin layer and the resin film, the method comprising:

applying a wet coating composition to a releasable surface, the wet composition containing a resin, a first solvent capable of dissolving the resin, and a second solvent substantially incapable of dissolving the resin;

drying the applied composition to form the thin resin layer and the porous resin layer simultaneously as a continuous unitary body on the releasable surface;

separating the unitary body formed by the thin resin layer and the porous resin layer from the releasable surface; and

bonding the resin film to the thin resin layer of the unitary body.

20. (new) The method as set forth in claim 13, further comprising forming a non-resinous porous layer on the porous resin layer.

D1 (continued)

21. (new) The method as set forth in claim 13, wherein the heat-sensitive stencil has a flexural rigidity of at least 10 mN.

22. (new) The method as set forth in claim 13, wherein an adhesion strength between the thin resin layer and the resin film is at least 1.0 kg/cm^2.

23. (new) The method as set forth in claim 13, wherein a thickness of the thin resin layer is in a range of 0.001 μm to 10 μm.

24. (new) The method as set forth in claim 13, wherein the resin film has at least one resin component which is the same as that of the thin resin layer.

25. (new) The method as set forth in claim 13, wherein the thin resin layer has at least one resin component which is the same as that of the porous resin layer.

26. (new) The method as set forth in claim 13, further comprising winding the heat-sensitive stencil around a cylindrical core.

D1 (concluded)

27. (new) The method as set forth in claim 15, wherein the thin resin layer has no resin component which is common to that of the porous resin layer.